



**MAX
245°C**

**MSL
1**

PRODUCT FAMILY	Material	CAS Number	% Normalize for BOM	Wt. Of BOM Item (g)	% by Wt (Comp. Item)	mg/unit	% by Wt Of Unit	ppm
767 16							266.00	
Alumina Ceramic	Al2O3	1344-28-1	0.8800	0.2341	87.50%	204.8200	77.00%	770000
	SiO2 (silicon dioxide)	14808-60-7			12.50%	29.2600	11.00%	110000
					100.00%	234.0800		
Conductor Thick Film	Ag	7440-22-4	0.0068	0.0018	99.00%	1.7907	0.67%	6732
	Pd	7440-05-3			1.00%	0.0181	0.01%	68
					100.00%	1.8088		
Resistor Thick Film	RuO2	12036-10-1	0.0079	0.0021	30.00%	0.6304	0.24%	2370
	PbO	1317-36-8			10.00%	0.2101	0.08%	790
	SiO2 (silicon dioxide)	14808-60-7			30.00%	0.6304	0.24%	2370
	B2O3	1303-86-2			30.00%	0.6304	0.24%	2370
					100.00%	2.1014		
Notch Conductor Thick Film	Ag	7440-22-4	0.0113	0.0030	72.02%	2.1648	0.81%	8138
	Pd	7440-05-3			4.20%	0.1262	0.05%	475
	Pt	7440-06-4			23.78%	0.7148	0.27%	2687
					100.00%	3.0058		
Lead Wire	Cu	7440-50-8	0.0376	0.0100	100.00%	10.0016	3.76%	37600
Solder	Pb	7439-92-1	0.0376	0.0100	90.00%	9.0014	3.38%	33840
	Sn	7440-31-5			10.00%	1.0002	0.38%	3760
					100.00%	10.0016		
Covercoat	TiO2	13463-67-7	0.0188	0.0050	50.00%	2.5004	0.94%	9400
	Phenolic Resin	55185-45-0			25.00%	1.2502	0.47%	4700
	Epoxy Resin	25068-38-6			25.00%	1.2502	0.47%	4700
	Sum		1.0000	0.2660	100.00%	5.0008		
				part weight	0.2660			
		Totals:		0.2660		266.00	100.00%	1000000